



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B5V1*L145CAD	A	BO2A	2016-06-20
Amount	UoM	Unit type	ST ECOPACK Grade	
5540.00	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
N/A	N/A	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SVP	20x 17.40x 4.42	11	Through-hole	
Comment	Package: V1 MULTIWATT 11L SPLIT VERT.; MDF valdi for TDA7265A			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	BSV1*L145CAD					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	8.133	mg	supplier	die	Silicon (Si)	7440-21-3		7.877	mg	968523	1422
				supplier	metallization	Aluminium (Al)	7429-90-5		0.098	mg	12050	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.034	mg	4180	6
				supplier	Passivation	Silicon Oxide	7631-86-9		0.048	mg	5902	9
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.006	mg	738	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.016	mg	1967	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.054	mg	6640	10
Leadframe	Copper & its alloys	4502.329	mg	supplier	alloy	Copper (Cu)	7440-50-8		4492.180	mg	997746	810863
				supplier	alloy	Iron (Fe)	7439-89-6		2.069	mg	460	373
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		3.778	mg	839	682
				supplier	metallization	Silver (Ag)	7440-22-4		4.302	mg	956	777
Soft solder	Solder	6.810	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.640	mg	975037	1199
				supplier	solder	Silver (Ag)	7440-22-4		0.102	mg	14978	18
				supplier	solder	Tin (Sn)	7440-31-5		0.068	mg	9985	12
Bonding wires	Precious metals	1.510	mg	supplier	wire	Gold (Au)	7440-57-5		1.510	mg	1000000	273
Encapsulation	Other Organic Materials	998.452	mg	supplier	mold compound	Silica, vitreous	60676-86-0		715.890	mg	717000	129222
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		169.737	mg	170000	30638
				supplier	mold compound	Phenol resin	9003-35-4		71.889	mg	72000	12976
				supplier	mold compound	Brominated epoxy resin	40039-93-8		14.977	mg	15000	2703
				supplier	mold compound	Antimony Trioxide	1309-64-4		19.969	mg	20000	3605
				supplier	mold compound	Bismuth	7440-69-9		2.995	mg	3000	541
connections coating	Solder	22.766	mg	supplier	mold compound	Carbon black	1333-86-4		2.995	mg	3000	541
				supplier	solder alloy	Tin (Sn)	7440-31-5		22.766	mg	1000000	4109